

Vishay Semiconductors

Power MOSFET, 180 A



SOT-227

100 V

180 A

0.0065 Ω

Modules - MOSFET

SOT-227

PRODUCT SUMMARY

V_{DSS}

 $I_D DC$

R_{DS(on)}

Type

Package

FEATURES

- · Fully isolated package
- · Easy to use and parallel
- · Very low on-resistance
- Dynamic dV/dt rating
- · Fully avalanche rated
- Simple drive requirements
- · Low drain to case capacitance
- Low internal inductance
- UL pending
- Compliant to RoHS directive 2002/95/EC

DESCRIPTION

5th Generation, high current density Power MOSFETs are paralled into a compact, high power module providing the best combination of switching, ruggedized design, very low on resistance and cost effectiveness.

The isolated SOT-227 package is preferred for all commercial-industrial applications at power dissipation levels to approximately 500 W. The low thermal resistance and easy connection to the SOT-227 package contribute to its universal acceptance throughout the industry.

| ABSOLUTE MAXIMUM RATINGS | | | | |
|--|-----------------------------------|-------------------------|---------------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS |
| Continuous drain current at V _{GS} 10 V | ۱ _D | T _C = 25 °C | 180 | |
| | | T _C = 100 °C | 120 | A |
| Pulsed drain current | I _{DM} ⁽¹⁾ | | 720 | |
| Power dissipation | PD | T _C = 25 °C | 480 | W |
| Linear derating factor | | | 2.7 | W/°C |
| Gate to source voltage | V _{GS} | | ± 20 | V |
| Single pulse avalanche energy | E _{AS} ⁽²⁾ | | 700 | mJ |
| Avalanche current | I _{AR} ⁽¹⁾ | | 180 | A |
| Repetitive avalanche energy | E _{AR} ⁽¹⁾ | | 48 | mJ |
| Peak diode recovery dV/dt | dV/dt ⁽³⁾ | | 5.7 | V/ns |
| Operating junction and storage temperature range | T _J , T _{Stg} | | - 55 to + 150 | °C |
| Insulation withstand voltage (AC-RMS) | V _{ISO} | | 2.5 | kV |
| Mounting torque | | M4 screw | 1.3 | Nm |

Notes

⁽¹⁾ Repetitive rating; pulse width limited by maximum junction temperature (see fig. 8)

 $^{(2)}$ Starting T_J = 25 °C, L = 43 $\mu H,~R_g$ = 25 $\Omega,~I_{AS}$ = 180 A (see fig. 12)

⁽³⁾ $I_{SD} \le 180$ A, dl/dt ≤ 83 A/µs, $V_{DD} \le V_{(BR)DSS}$, $T_J \le 150$ °C

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| THERMAL RESISTANCE | | | | |
|-------------------------------------|-------------------|------|------|-------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNITS |
| Junction to case | R _{thJC} | - | 0.26 | °C/W |
| Case to sink, flat, greased surface | R _{thCS} | 0.05 | - | 0/10 |

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
|---|------------------------------------|--|------|--------|-------|-------|
| Drain to source breakdown voltage | V(_{BR)DSS} | $V_{GS} = 0 \text{ V}, I_D = 250 \ \mu\text{A}$ | 100 | - | - | V |
| Breakdown voltage temperature coefficient | $\Delta V_{(BR)DSS} / \Delta T_J$ | Reference to 25 °C, I _D = 1 mA | - | 0.093 | - | V/°C |
| Static drain to source on-resistance | R _{DS(on)} ⁽¹⁾ | $V_{GS} = 10 \text{ V}, I_D = 180 \text{ A}$ | - | 0.0065 | - | Ω |
| Gate threshold voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 2.0 | - | 4.0 | V |
| Forward transconductance | 9 _{fs} | V _{DS} = 25 V, I _D = 180 A | 93 | - | - | S |
| Drain to source leakage current | | $I_{DSS} \qquad \begin{array}{c} V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V} \\ V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C} \end{array}$ | - | - | 50 | μΑ |
| | IDSS | | - | - | 500 | |
| Gate to source forward leakage | | $I_{GSS} \qquad \frac{V_{GS} = 20 V}{V_{GS} = -20 V}$ | - | - | 200 | nA |
| | IGSS | | - | - | - 200 | |
| Total gate charge | Qg | I _D = 180 A | - | 250 | 380 | |
| Gate to source charge | Q _{gs} | V _{DS} = 80 V | - | 40 | 60 | nC |
| Gate to drain ("Miller") charge | Q _{gd} | V_{GS} = 10.0 V; see fig. 6 and 13 ⁽¹⁾ | - | 110 | 165 | 1 |
| Turn-on delay time | t _{d(on)} | V _{DD} = 50 V | - | 45 | - | |
| Rise time | t _r | $I_{\rm D} = 180 \rm{A}$ | - | 351 | - | 1 |
| Turn-off delay time | t _{d(off)} | $R_g = 2.0 \Omega$ (internal) | - | 181 | - | ns |
| Fall time | t _f | $R_{\rm D}$ = 0.27 Ω, see fig. 10 ⁽¹⁾ | - | 335 | - | 1 |
| Internal source inductance | L _S | Between lead, and center of die contact | - | 5.0 | - | nH |
| Input capacitance | C _{iss} | $V_{GS} = 0 V$ | - | 10 700 | - | |
| Output capacitance | C _{oss} | $V_{DS} = 25 V$ | - | 2800 | - | pF |
| Reverse transfer capacitance | C _{rss} | f = 1.0 MHz, see fig. 5 | - | 1300 | - | 1 |

Note

 $^{(1)}\,$ Pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|--------------------------------|---|------|------|------|------|
| Continuous source current (body diode) | ١ _S | MOSFET symbol | - | - | 180 | |
| Pulsed source current (body diode) | I _{SM} ⁽¹⁾ | showing the integral reverse p-n junction diode. | - | - | 720 | |
| Diode forward voltage | V _{SD} ⁽²⁾ | T_J = 25 °C, I_S = 180 A, V_{GS} = 0 V | - | - | 1.3 | V |
| Reverse recovery time | t _{rr} ⁽²⁾ | | - | 300 | 450 | ns |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C, I _F = 180 A; dl/dt = 100 A/μs | - | 2.6 | 3.9 | μC |
| Forward turn-on time | t _{on} | Intrinsic turn-on time is negligible (turn-on is dominated by $L_{S} + L_{D}$) | | | | |

Notes

⁽¹⁾ Repetitive rating; pulse width limited by maximum junction temperature (see fig. 8)

⁽²⁾ Pulse width \leq 300 µs, duty cycle \leq 2 %

For technical questions within your region, please contact one of the following: <u>DiodesAmericas@vishay.com</u>, <u>DiodesAsia@vishay.com</u>, <u>DiodesEurope@vishay.com</u>

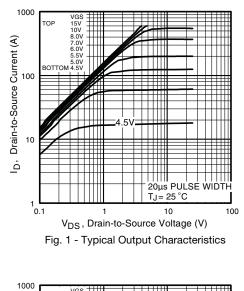


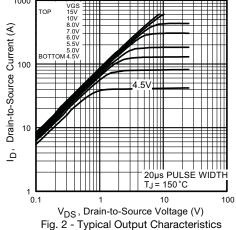
Not Available for New Designs, Use VS-FB190SA10

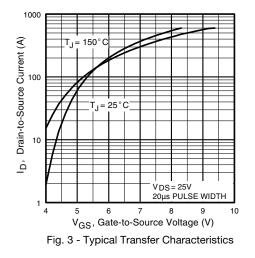
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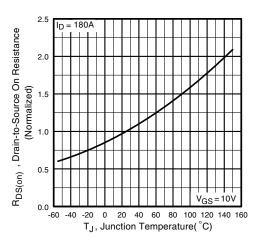
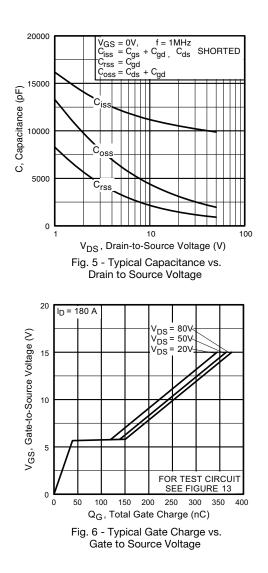


Fig. 4 - Normalized On-Resistance vs. Temperature



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200



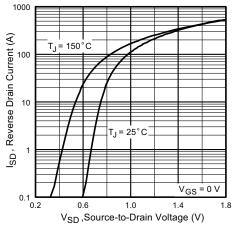
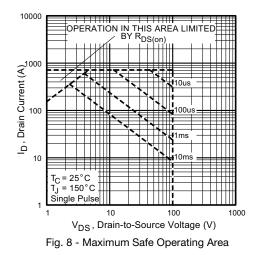


Fig. 7 - Typical Source Drain Diode Forward Voltage



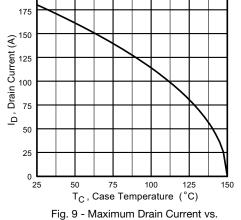
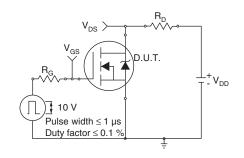
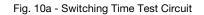


Fig. 9 - Maximum Drain Current vs. Case Temperature





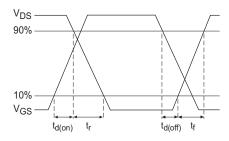


Fig. 10b - Switching Time Waveforms



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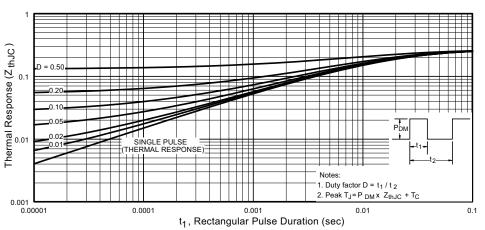


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction to Case

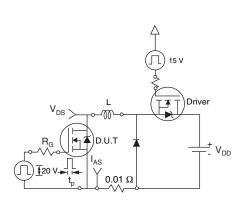


Fig. 12a - Unclamped Inductive Test Circuit

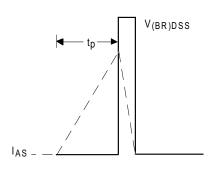


Fig. 12b - Unclamped Inductive Waveforms

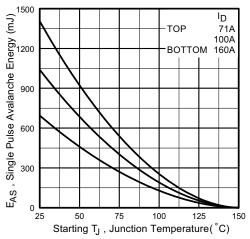


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

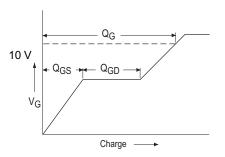


Fig. 13a - Basic Gate Charge Waveform

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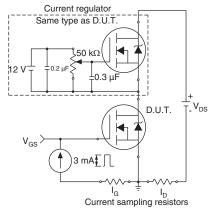


Fig. 13b - Gate Charge Test Circuit

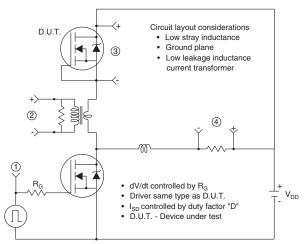
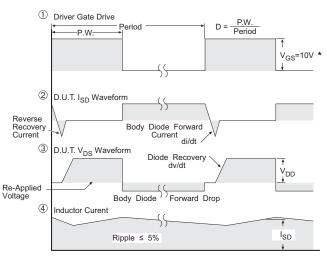


Fig. 13c - Peak Diode Recovery dV/dt Test Circuit



* V_{GS} = 5V for Logic Level Devices

Fig. 14 - For N-Channel Power MOSFETs

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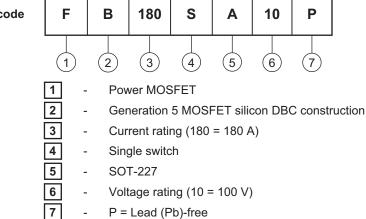


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ORDERING INFORMATION TABLE

Device code



| CIRCUIT CONFIGURATION | | | | |
|------------------------|-------------------------------|---|--|--|
| CIRCUIT | CIRCUIT CONFIGURATION CODE | CIRCUIT DRAWING | | |
| Single switch no diode | S | G (2) $G (2)$ $G (2)$ $G (2)$ $G (2)$ $G (1-4)$ $C (1-4)$ $C (3)$ $C (1-4)$ $C (3)$ $C (1-4)$ | | |

| LINKS TO RELATED DOCUMENTS | | | |
|----------------------------|--------------------------|--|--|
| Dimensions | www.vishay.com/doc?95036 | | |
| Packaging information | www.vishay.com/doc?95037 | | |

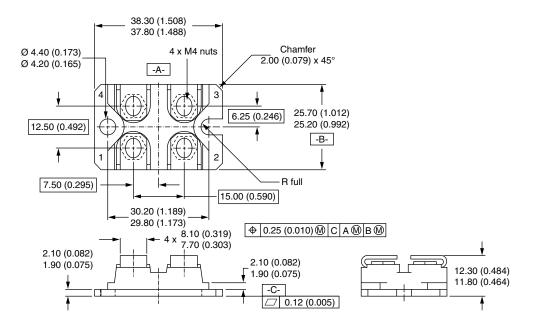


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SOT-227

DIMENSIONS in millimeters (inches)



Notes

- Dimensioning and tolerancing per ANSI Y14.5M-1982
- Controlling dimension: millimeter



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